

LAMINATE AND METHOD FOR PRODUCING SAME**ABSTRACT**

The object of the present invention is to provide a metallic material which can be employed as a constituent member of a semiconductor production device and has excellent corrosion resistance. A laminate according to the present invention comprises a metallic base material, a nickel-containing plating film layer formed on the metallic base material, and a gold plating film layer formed on the nickel-containing plating film layer, in which pinholes in the gold plating film layer are sealed with a fluorinated passive film having a thickness of 8 nm or greater.

[Fig. 1]